

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	
)	Docket No.: 660073.553
Gurtej S. Sandhu)	Disclosure Number: 95-0717
)	
Serial No.:)	Group Art Unit:
)	
Filed: Concurrently herewith)	Examiner:
)	
For: METHOD AND APPARATUS)	
FOR ENDPOINTING)	
MECHANICAL AND)	
CHEMICAL-MECHANICAL)	
POLISHING OF SUBSTRATES)	
)	

ASSIGNMENT:

 X Enclosed for recording
 Previously recorded
Date: _____
Reel: _____

A S S I G N M E N T

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned does hereby:

SELL, ASSIGN AND TRANSFER to Micron Technology, Inc. (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, P.O. Box 6, Boise, Idaho 83707-0006, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled **"METHOD AND APPARATUS FOR ENDPOINTING MECHANICAL AND CHEMICAL-MECHANICAL POLISHING OF SUBSTRATES"**; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

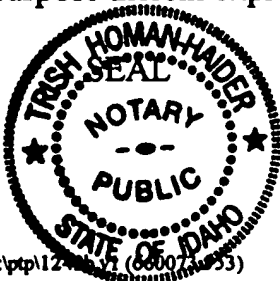
Gurtej S. Sandhu

Date: August 15, 1997

STATE OF IDAHO)

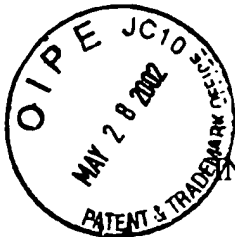
County of Ada) ss.

BEFORE ME, this 15th day of August, 1997, personally appeared the above-named individual, to me known to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he executed the same of his own free will for the purpose therein expressed.



Lizeth Roman-Valdes
Notary or Consular Officer
My Commission Expires 7-26-2003

**COPY OF PAPERS
ORIGINALLY FILED**



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Reissue Patent Application:

Applicant : Gurtej S. Sandhu
Assignee: : Micron Technology, Inc.
Filed : December 28, 2001
For : METHOD AND APPARATUS FOR ENDPOINTING MECHANICAL AND
CHEMICAL-MECHANICAL POLISHING OF SUBSTRATES
Docket No. : 500042.02

Corresponding Issued U.S. Patent:

Patent No. : 6,007,408
Issued : December 28, 1999
Application No. : 08/917,665
Filing Date : August 21, 1997
Examiner : George Nguyen
Art Unit : 3723

BOX REISSUE
Commissioner for Patents
Washington, DC 20231

ASSENT OF ASSIGNEE

Sir:

The undersigned, Micron Technology, Inc. (hereinafter "Micron"), a corporation of the State of Delaware having a place of business at 8000 South Federal Way, Boise, Idaho 83716, declares that it is the assignee of the entire right, title, and interest in the above-identified U.S. Patent No. 6,007,408. Documentary evidence of chain of title from the original owner to Micron has been filed with and recorded by the United States Patent Office at Reel 8781, Frame 0755. The evidentiary documents referred to in the instant Assent of Assignee have been reviewed by the undersigned and it is certified that, to the best of Micron's knowledge and belief, title is in Micron.

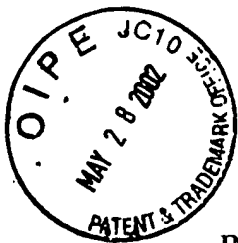
The undersigned Assignee hereby assents to the reissue application.

Micron Technology, Inc.

Date

By: 2-13-2002

Michael L. Lynch
Chief Patent Counsel



EXPRESS MAIL NO. EL 872037744 US

Serial No. 10/035,828

PATENT

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Washington, DC 20231

COPY OF PAPERS
ORIGINALLY FILED

OFFER TO SURRENDER THE ORIGINAL PATENT

Sir:

Michael L. Lynch, Chief Patent Counsel of the Assignee of the entire interest in U.S. Letters Patent No. 6,007,408 which is entitled METHOD AND APPARATUS FOR ENDPOINTING MECHANICAL AND CHEMICAL-MECHANICAL POLISHING OF SUBSTRATES and issued on December 28, 1999, to Micron Technology, Inc., hereby offers to surrender said Letters Patent.

Micron Technology, Inc.

2-13-2002
Date

By: [Signature]
Michael L. Lynch
Chief Patent Counsel